

SOT1444-3

wafer level chip-scale package; 49 bumps; 2.98 x 3.43 x 0.56 mm

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP
Package type industry code	WLCSP49
Package style descriptive code	UC (uncased chip)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	21-7-2015

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	3.4	-	3.43	3.46	mm
E	package width	2.95	-	2.98	3.01	mm
A	seated height	0.52	-	0.56	0.6	mm
A ₂	package height	0.335	-	0.36	0.385	mm
e	nominal pitch	-	-	0.4	-	mm
n ₂	actual quantity of termination	-	-	49	-	



2. Package outline

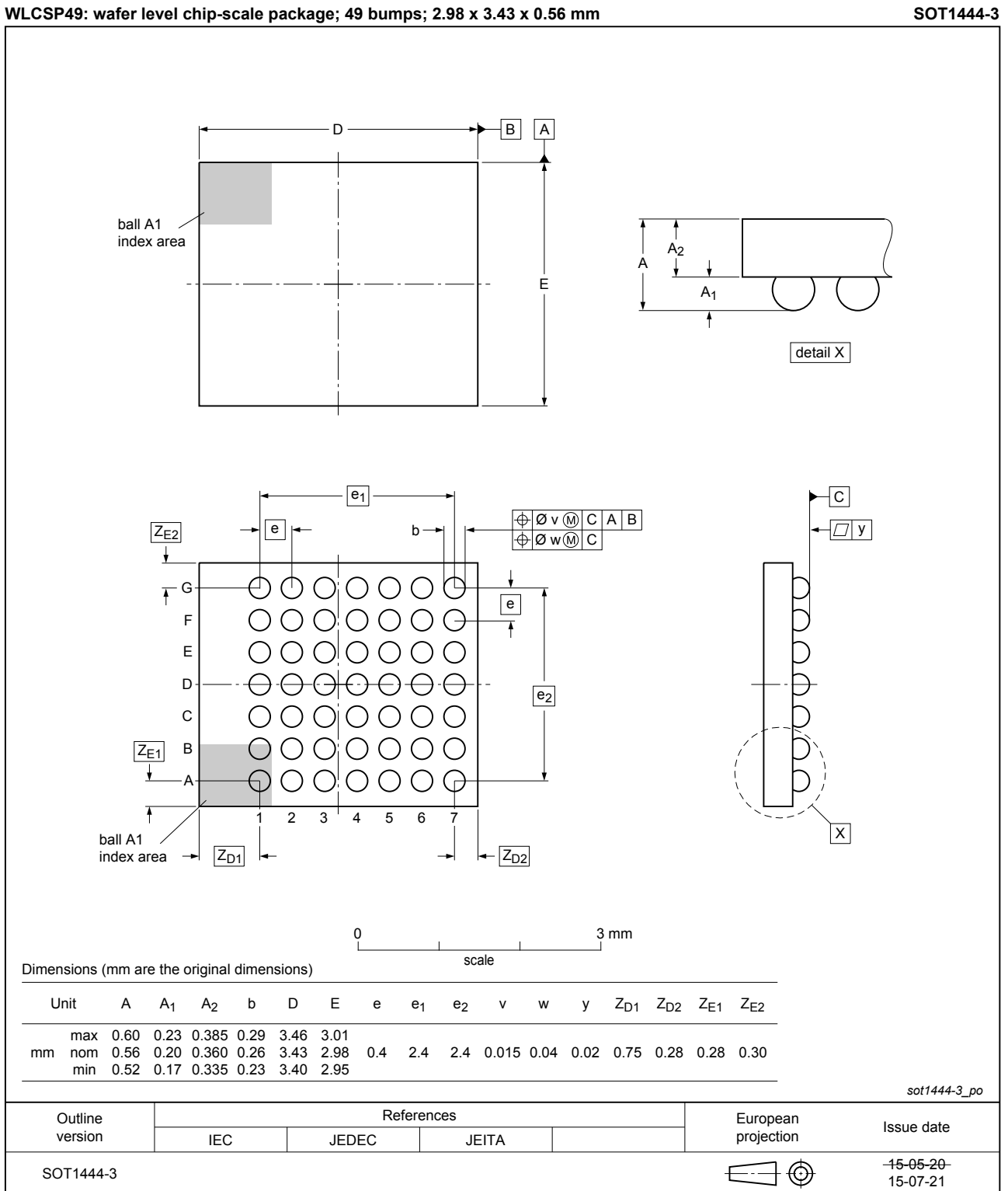


Fig. 1. Package outline WLCSP49 (SOT1444-3)

3. Legal information

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Date of release: 8 February 2016
